



Integrated Circuit and Antenna Design for Millimeter-Wave and Terahertz Communication

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Deadline for manuscript
submissions:

closed (30 November 2022)

Message from the Guest Editors

Dear Colleagues,

This Special Issue offers a premier interdisciplinary platform for researchers to disseminate their results in all areas of integrated circuit and antenna design to a diverse audience in an open access format. The present Special Issue is focused on presenting technical papers covering the various aspects of the front-end transceiver, ADC/DAC conversions, and the basic baseband functions, designed to address the new requirements at the system and circuit levels. This Special Issue focuses on the recent advances in THz wireless communications based either on electronics or photonics approaches, with an emphasis on THz passive and active components, THz devices and packaging, THz antennas and beam-steering techniques, modulation, and waveform design for THz channels. To that end, we invite authors to submit their original and previously unpublished research papers and comprehensive reviews in the following or related topics of millimeter wave (mmWave) and terahertz communication and beyond:

- mmWave Communication
- terahertz communication
- wireless communications
- antenna beamforming
- integrated circuits





Editor-in-Chief

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Message from the Editor-in-Chief

I would like to introduce the new, online, and open access journal *Telecom*. The purpose of *Telecom* is to publish high-quality research papers as well as review articles that address recent advances in communications technology. We invite researchers to contribute original papers describing applications and experiences in emerging trends of all fields of telecommunications engineering. *Telecom* also welcomes Special Issue proposals from academics and industrial researchers. We aim to facilitate more collaboration between scientists and engineers around the world, such that they will produce their innovative ideas and submit their cutting-edge technologies to *Telecom*. We anticipate the receipt of your contributions to *Telecom*, and we welcome your comments and ideas on how to improve this journal.

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